

## **REMARKS**

Claims 1 and 3-9 are now pending in the above-referenced application and are submitted for the Examiner's reconsideration.

The Examiner, in numbered paragraph 7, states that the patentability arguments made in the last response are not commensurate in scope with the claims, since, in the opinion of the Examiner, the claims do not exclude an indirect bonding between a cap and glass layer. In response, Applicants have amended claim 1 to recite expressly such a direct bonding.

Sparks et al. (6062461) shows the bonding of two wafers 10, 12 via a soldering connection – that is, not a direct bonding of a cap to the glass layer of a carrier. Sparks et al. does not disclose the bonding of a component structure having a first silicon layer directly to the glass layer.

Sparks et al. (5831162) shows the bonding of a sensor structure 12 to an integrated circuit 16 via contact surfaces 20, 24, 25 and balls of solder 22 arranged in between, that is, not a direct bonding. Sparks et al. (5831162) thus also does not disclose the bonding of a component structure having a first silicon layer directly to the glass layer.

Regan et al. (6686642) shows the mutual bonding of two substrates, one having an etched and a second having a non-etched surface. The bonding occurs via intermediate layers 14, 18 or via a seal 56. Again, a direct bonding of a cap to a glass layer of a carrier is not disclosed.

As already stated in the last response, Maluf et al. does not show the direct bonding of the cap to the glass layer. Instead, it shows the bonding of a second layer to a first layer and the bonding of a third layer to a second layer. Maluf et al. in particular also does not show a cap, for the cavity is essentially defined by the second layer that is situation between the first and the third layer.

Thus none of the cited references show a direct bonding of a cap to a glass layer of a carrier.

The present invention is new, non-obvious, and useful. Reconsideration and allowance of the presently pending claims are respectfully requested.

Respectfully submitted,

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